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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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



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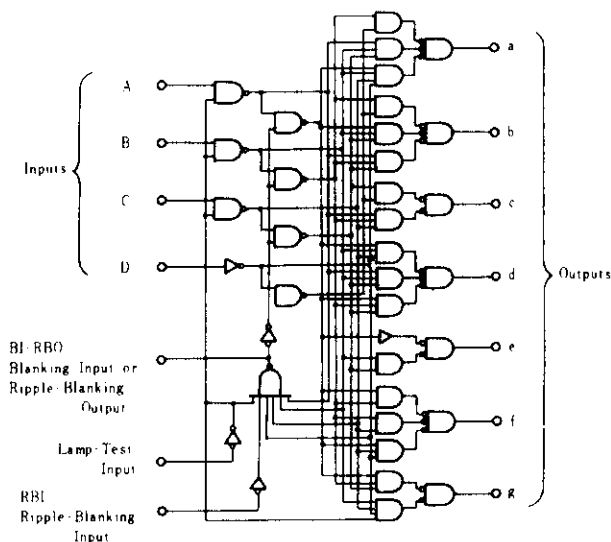
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HD74LS248 • BCD-to-Seven-Segment Decoders/Drivers (internal pull-up outputs)

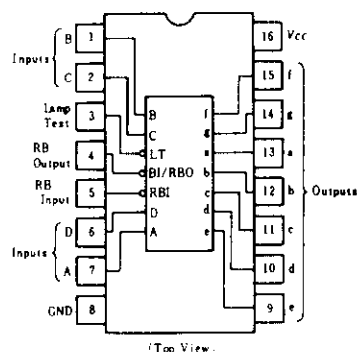
The HD74LS248 is electrically and functionally identical to the HD74LS48, respectively, and has the same pin assignments as its equivalents. It can be used interchangeably in present or future designs to offer designers a choice between two indicator fonts. The HD74LS48 composes the  and the  with-out tails and the HD74LS248 composes the  and the  with tails. Composition of all other characters, including display patterns for BCD inputs above nine, is identical. The HD74LS248 features active-low outputs designed for driving indicators directly. All of the circuits have full ripple-blanking input/output controls and a lamp test input. Segment identification and resultant displays are shown below. Display patterns for BCD input counts above 9 are unique symbols to authenticate input conditions. This circuit incorporates automatic leading and/or trailing-edge zero-blanking control (RBI and RBO).

Lamp test (LT) of this type may be performed at any time when the BI/RBO node is at a high level. This type contains an overriding blanking input (BI) which can be used to control the lamp intensity by pulsing or to inhibit the outputs.

■ BLOCK DIAGRAM

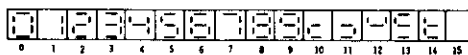


■ PIN ARRANGEMENT



■ RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
Output current	a ~ g	—	—	~ 100	μA
	BI/RBO	—	—	~ 50	
	a ~ g	—	—	6	mA
	BI/RBO	—	—	3.2	



FUNCTION TABLE

Decimal or Function	Inputs						BI/RBO	Outputs							Note
	LT	RBI	D	C	B	A		a	b	c	d	e	f	g	
0	H	H	L	L	L	L	H	H	H	H	H	H	H	L	1
1	H	X	L	L	L	H	H	L	H	H	L	L	L	L	
2	H	X	L	L	H	L	H	H	H	L	H	H	L	H	
3	H	X	L	L	H	H	H	H	H	H	H	L	L	H	
4	H	X	L	H	L	L	H	L	H	H	L	L	H	H	
5	H	X	L	H	L	H	H	H	L	H	H	L	H	H	
6	H	X	L	H	H	L	H	H	L	H	H	H	H	H	
7	H	X	L	H	H	H	H	H	H	H	L	L	L	L	
8	H	X	H	L	L	L	H	H	H	H	H	H	H	H	
9	H	X	H	L	L	H	H	H	H	H	H	L	H	H	
10	H	X	H	L	H	L	H	L	L	L	H	H	L	H	
11	H	X	H	L	H	H	H	L	L	H	H	L	L	H	
12	H	X	H	H	L	L	H	L	H	L	L	L	H	H	
13	H	X	H	H	L	H	H	H	L	L	H	L	H	H	
14	H	X	H	H	H	L	H	L	L	L	H	H	H	H	
15	H	X	H	H	H	H	H	L	L	L	L	L	L	L	
BI	X	X	X	X	X	X	L	L	L	L	L	L	L	L	2
RBI	H	L	L	L	L	L	L	L	L	L	L	L	L	L	3
LT	L	X	X	X	X	X	H	H	H	H	H	H	H	H	4

H; high level, L; low level, X; irrelevant

- Notes: 1. The blanking input (BI) must be open or held at a high-logic level when output functions 0 through 15 are desired.
 2. When a low logic level is applied directly to the blanking input.
 3. When ripple-blanking input (RBI) and inputs A, B, C, and D

are at a low level with the lamp-test input high, all segment outputs go low and the ripple-blanking output (RBO) goes to a low level (response condition).

4. When a blanking input/ripple blanking output (BI/RBO) is open or held high and a low is applied to the lamp-test input, all segment outputs are high.

ELECTRICAL CHARACTERISTICS (Ta = -20 ~ +75°C)

Item		Symbol	Test Conditions		min	typ*	max	Unit	
Input voltage		V_{IH}			2.0	—	—	V	
		V_{IL}			—	—	0.8	V	
Output voltage	a~g	V_{OH}	$V_{CC}=4.75V, V_{IH}=2V$	$I_{OH}=-100\mu A$	2.4	—	—	V	
	BI/RBO		$V_{IL}=0.8V$	$I_{OH}=-50\mu A$					
Output current**	a~g	I_O	$V_{CC}=4.75V, V_O=0.85V$		-1.3	—	—	mA	
Output voltage	a~g	V_{OL}	$V_{CC}=4.75V, V_{IH}=2V$ $V_{IL}=0.8V$	$I_{OL}=2mA$	—	—	0.4	V	
				$I_{OL}=6mA$	—	—	0.5		
	BI/RBO			$I_{OL}=1.6mA$	—	—	0.4		
				$I_{OL}=3.2mA$	—	—	0.5		
Input current	except BI/RBO	I_{IH}	$V_{CC}=5.25V, V_I=2.7V$		—	—	20	μA	
	except BI/RBO	I_{IL}	$V_{CC}=5.25V, V_I=0.4V$	—	—	-0.4	mA		
	BI/RBO			—	—	-1.2			
	except BI/RBO	I_I	$V_{CC}=5.25V, V_I=7V$		—	—	0.1	mA	
Short-circuit output current		BI/RBO	I_{OS}	$V_{CC}=5.25V$		-0.3	—	-2	mA
Supply current***			I_{CC}	$V_{CC}=5.25V$		—	25	38	mA
Input clamp voltage		V_{IK}	$V_{CC}=4.75V, I_{IN}=-18mA$		—	—	-1.5	V	

* $V_{CC}=5V, T_a=25^\circ C$

** Input condition as for V_{OH}

*** I_{CC} is measured with all outputs open and all inputs at 4.5V.

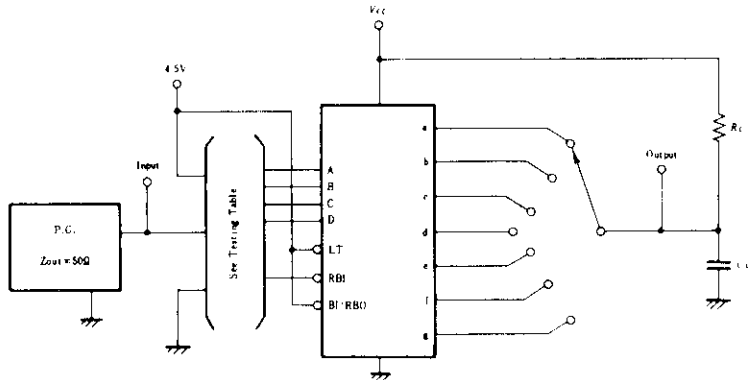
HD74LS248

SWITCHING CHARACTERISTICS ($V_{CC}=5V$, $T_a=25^{\circ}C$)

Item	Symbol	Input	Test Conditions	min	typ	max	Unit
Propagation delay time	t_{PLH}	A	$C_L=15pF$, $R_L=4k\Omega$	—	—	100	ns
	t_{PHL}			—	—	100	
	t_{PLH}	RBI	$C_L=15pF$, $R_L=6k\Omega$	—	—	100	ns
	t_{PHL}			—	—	100	

TESTING METHOD

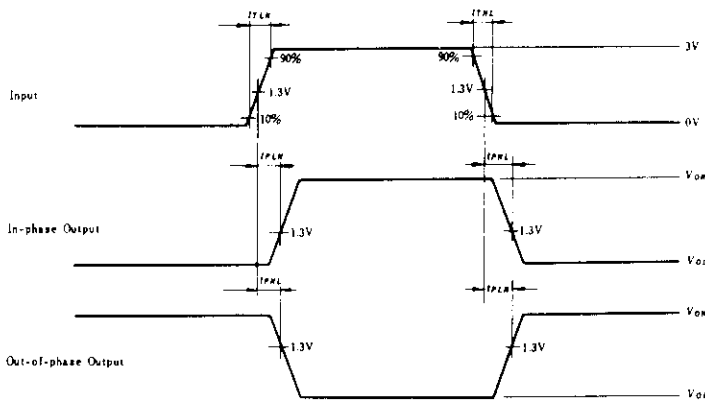
1) Test Circuit



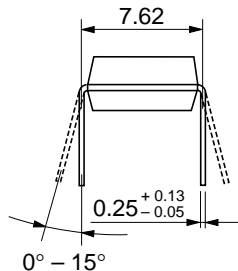
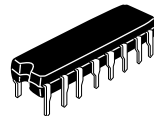
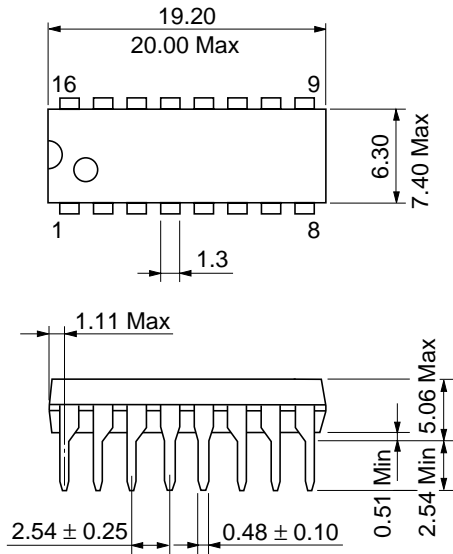
2) Testing Table

Item	Inputs					Outputs						
	RBI	D	C	B	A	a	b	c	d	e	f	g
t_{PLH}	4.5V	GND	GND	GND	IN	OUT	—	—	OUT	OUT	OUT	—
t_{PHL}	4.5V	GND	GND	4.5V	IN	—	—	OUT	—	OUT	—	—
	4.5V	GND	4.5V	4.5V	IN	—	OUT	—	OUT	OUT	OUT	OUT
	IN	GND	GND	GND	GND	OUT	OUT	OUT	OUT	OUT	OUT	—

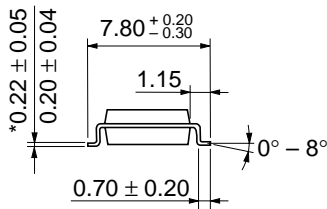
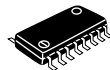
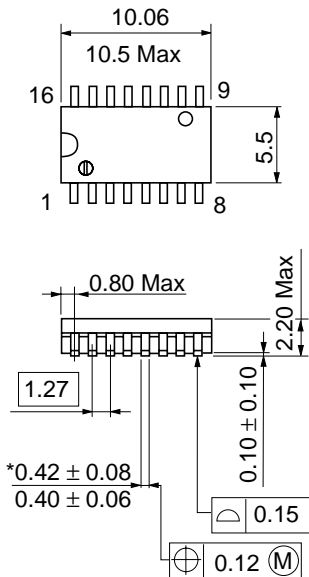
Waveform



- Notes) 1. Input pulse: $t_{TLH} \leq 15ns$, $t_{THL} \leq 6ns$, $PRR=1MHz$, duty cycle=50%
2. C_L includes probe and jig capacitance.

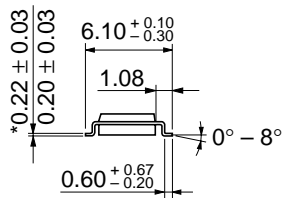
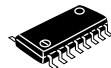
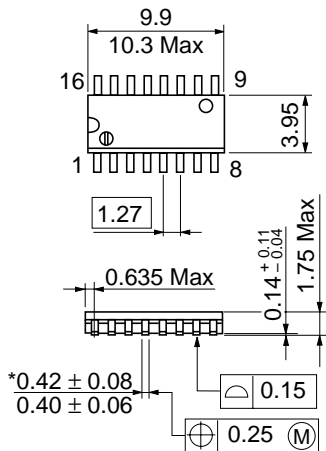


Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.07 g



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.24 g



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

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Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose, CA 95134 Tel: <1> (408) 433-1990 Fax: <1> (408) 433-0223	Hitachi Europe GmbH Electronic components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322
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Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

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